

ABSTRACT

A process for producing a laser engravable printing substrate, comprising the step of forming a layer of photosensitive resin composition on a cylindrical support or sheeted support and the step of irradiating the formed layer of photosensitive resin composition with light to thereby provide a layer of cured photosensitive resin of 50 μm to 50 mm thickness, wherein the light for irradiation of the photosensitive resin composition layer contains a ray of 200 to 450 nm wavelength and wherein the light illuminance on the surface of the photosensitive resin composition layer is in the range of 20 mW/cm^2 to 2 W/cm^2 when measured with the use of UV meter (trade name "UV-M02" manufactured by Ohku Seisakusho) and filter (trade name "UV-35-APR Filter" manufactured by Ohku Seisakusho) and in the range of 3 mW/cm^2 to 2 W/cm^2 when measured with the use of the above UV meter and filter (trade name "UV-25 Filter" manufactured by Ohku Seisakusho).